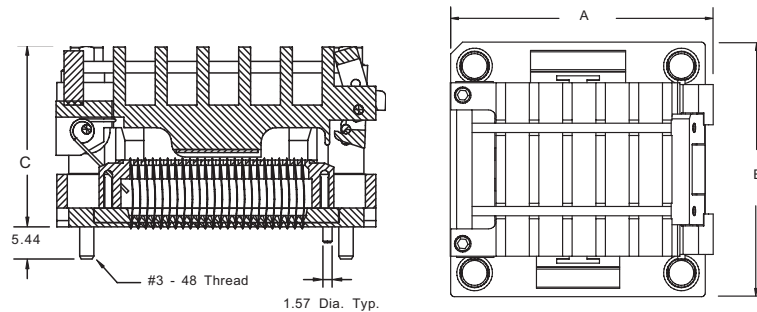


692 Series LGA Socket with Heatsink

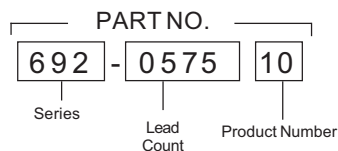
- Clamshell socket design is field replaceable
- Compression surface mount Buckle Beam contact
- Integrated heatsink in the lid for heat dissipation
- Pivoting heatsink for uniform compression of device
- Backer Plate required



Lead Count	Pitch e (mm)	Package Size (mm)	Matrix	Pad Dia. (mm)	Part Number
* 575	1.27	31 x 31	24 x 24	0.86	692-0575-09

* Full Cored Array 576 Leads

DESCRIPTION & ORDERING INFORMATION



MATERIALS & SPECIFICATIONS

- Socket Body: PEI or Equivalent
- Contacts (692): Beryllium Copper Alloy
- Contact Plating: Gold over Nickel
- Contact Durability: 10,000 cycles min.
- Temperature Rating: 150°C
- Insulation Resistance: 9 MΩ at 500V DC
- Contact Resistance: 100 mΩ max.
- Contact Current Rating: 1 Amp for 20°C rise
- Contact Self Inductance: 7 nH at 2 GHz
- Contact Mutual Inductance: 0.7 nH at 2 GHz
- Contact Mutual Capacitance: 0.05 pF at 2 GHz
- Contact Force: Average 20 grams